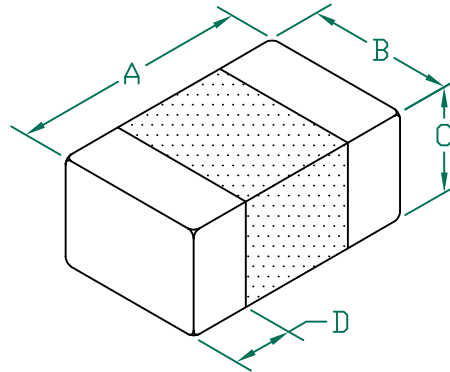


HZ0805E601R-10

**UNCONTROLLED
DOCUMENT**

PHYSICAL DIMENSIONS:

A	2.00 [.079]	± 0.20 [.008]
B	1.25 [.049]	± 0.20 [.008]
C	0.90 [.035]	± 0.20 [.008]
D	0.51 [.020]	± 0.25 [.010]

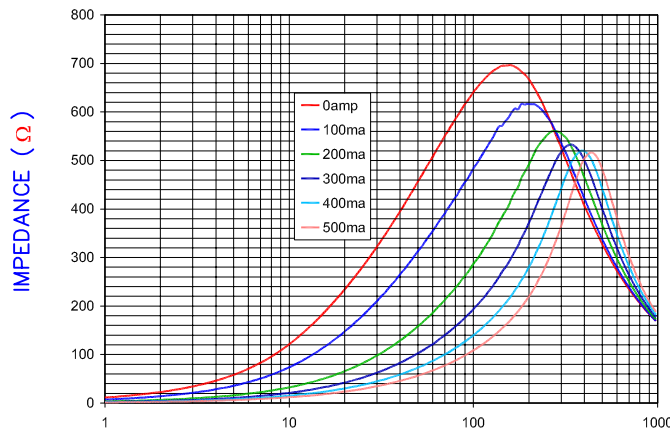


ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	600	
Minimum	450	
Maximum	750	0.300
		500 mA

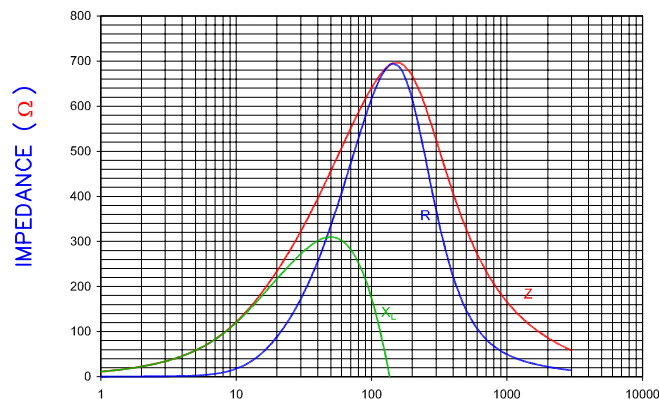
- NOTES: UNLESS OTHERWISE SPECIFIED
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
 3. TERMINATION FINISH IS 100% TIN.
 4. OPERATING TEMP. RANGE: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (INCLUDING SELF-HEATING)

Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)

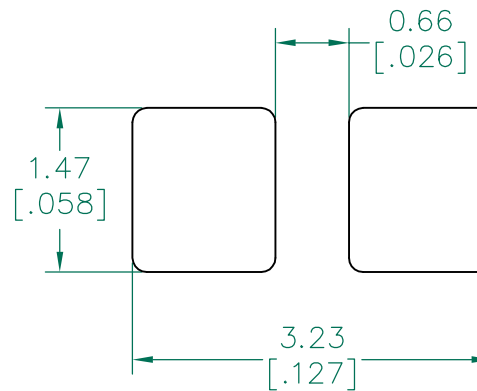
|Z|, R, AND X vs. FREQUENCY



FREQUENCY (MHz)

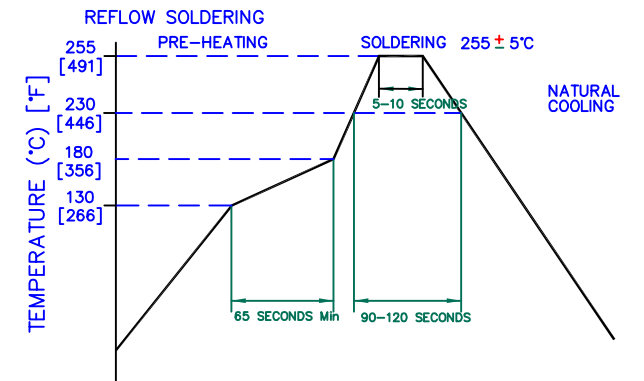
AGILENT E4991A RF Impedance/Material Analyzer
HP 16194A Test Fixture. TEST REF. 3228

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763
[.030] to this dimension.)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].

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E	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	PROJECT/PART NUMBER: HZ0805E601R-10	
D	CHANGE SOLDERING TEMPERATURE	08/23/10	JUN	REV E	PART TYPE: CO-FIRE
C	CHANGE TO PAPER TAPE	03/03/10	JUN	DRAWN BY: JRK	
B	UPDATE COMPANY LOGO ADD ROHS	03/21/08	JRK	DATE: 03/01/04	SCALE: NTS
A	ORIGINAL DRAFT	03/01/04	JRK	CAD # HZ0805E601R-10-E	SHEET: 2 of 2
REV	DESCRIPTION	DATE	INT	TOOL # -	